

US00D830321S

(12) **United States Design Patent**
Podubni

(10) **Patent No.:** **US D830,321 S**

(45) **Date of Patent:** **** Oct. 9, 2018**

(54) **MODULAR CIRCUIT BOARD**

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(73) Assignee: **TinyPCB, Inc.**

(**) Term: **15 Years**

(21) Appl. No.: **29/605,712**

(22) Filed: **May 30, 2017**

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 174/68.1, 250, 253, 255, 256;
318/567, 568.1; 361/600, 601, 718, 719,
361/720, 728, 736, 748, 751, 752, 760,
361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95

CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
H05K 3/363; H05K 3/40; H05K 7/14;
H05K 7/1422; H05K 7/00; H05K 1/18;
H05K 1/02; H05K 1/181; H05K 1/182;
H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2,896,033	A *	7/1959	Hartz	H01H 19/585 200/11 D
3,072,734	A *	1/1963	Fox	H02B 1/043 174/254
D279,670	S *	7/1985	Lukits	D13/182
4,602,271	A *	7/1986	Dougherty, Jr.	H01L 23/5385 257/697

4,715,928	A *	12/1987	Hamby	H05K 3/4691 156/150
D319,045	S *	8/1991	Hasegawa	D13/182
D319,629	S *	9/1991	Hasegawa	D13/182
D319,814	S *	9/1991	Hasegawa	D13/182
D397,093	S *	8/1998	Kim, II	D13/182
5,895,967	A *	4/1999	Stearns	H01L 23/3128 257/691
D429,704	S *	8/2000	Kang	D13/182
6,121,554	A *	9/2000	Kamikawa	H05K 1/113 174/255
D440,209	S *	4/2001	Kang	D13/182
D442,149	S *	5/2001	Kang	D13/182
D442,150	S *	5/2001	Kang	D13/182
D442,567	S *	5/2001	Kang	D13/182
D457,146	S *	5/2002	Yamamoto	D13/182
6,418,030	B1 *	7/2002	Yamaguchi	H01L 23/24 257/698
6,462,570	B1	10/2002	Price et al.		
D466,093	S *	11/2002	Ebihara	D13/182
D471,167	S *	3/2003	Ebihara	D13/182

(Continued)

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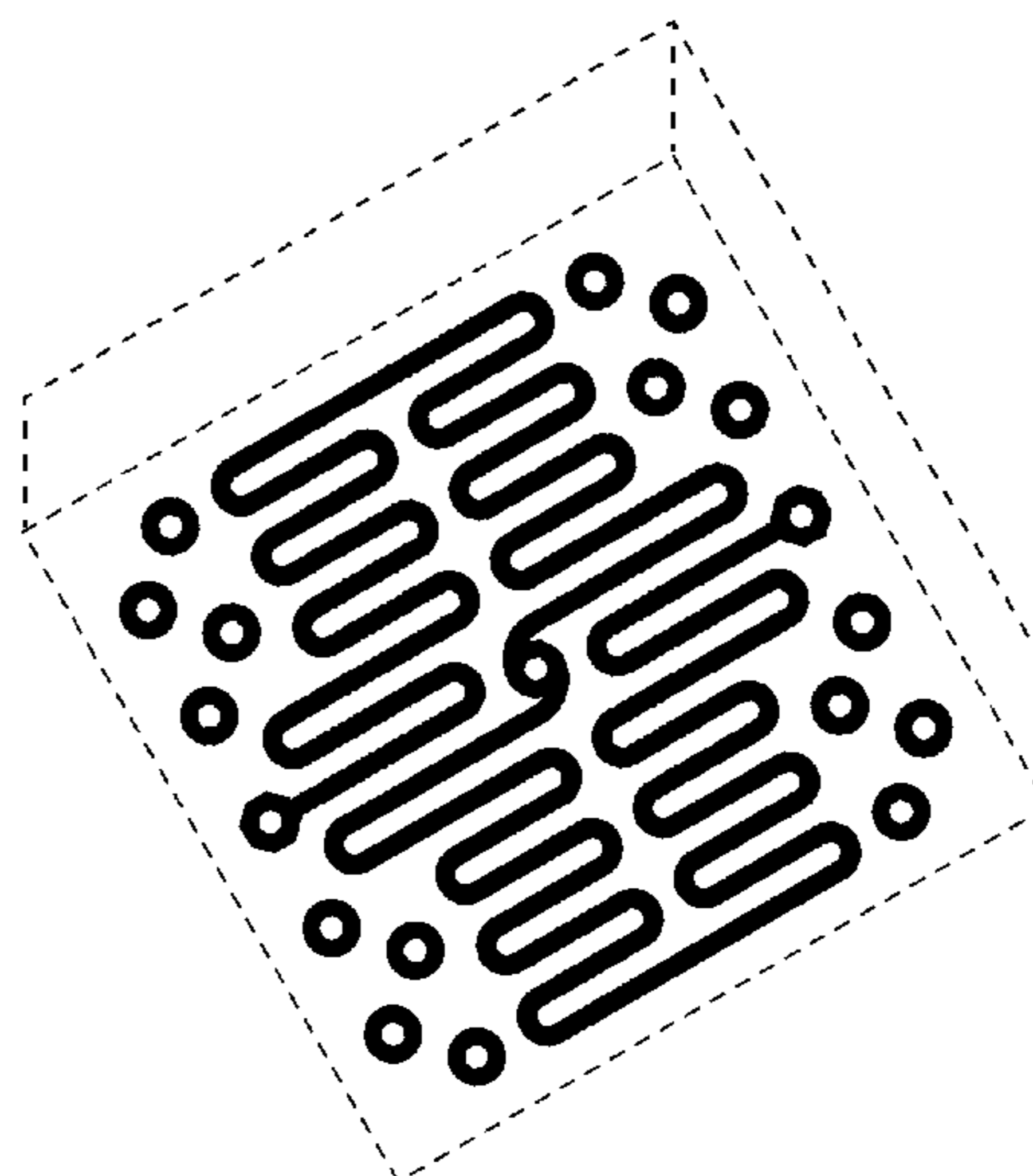
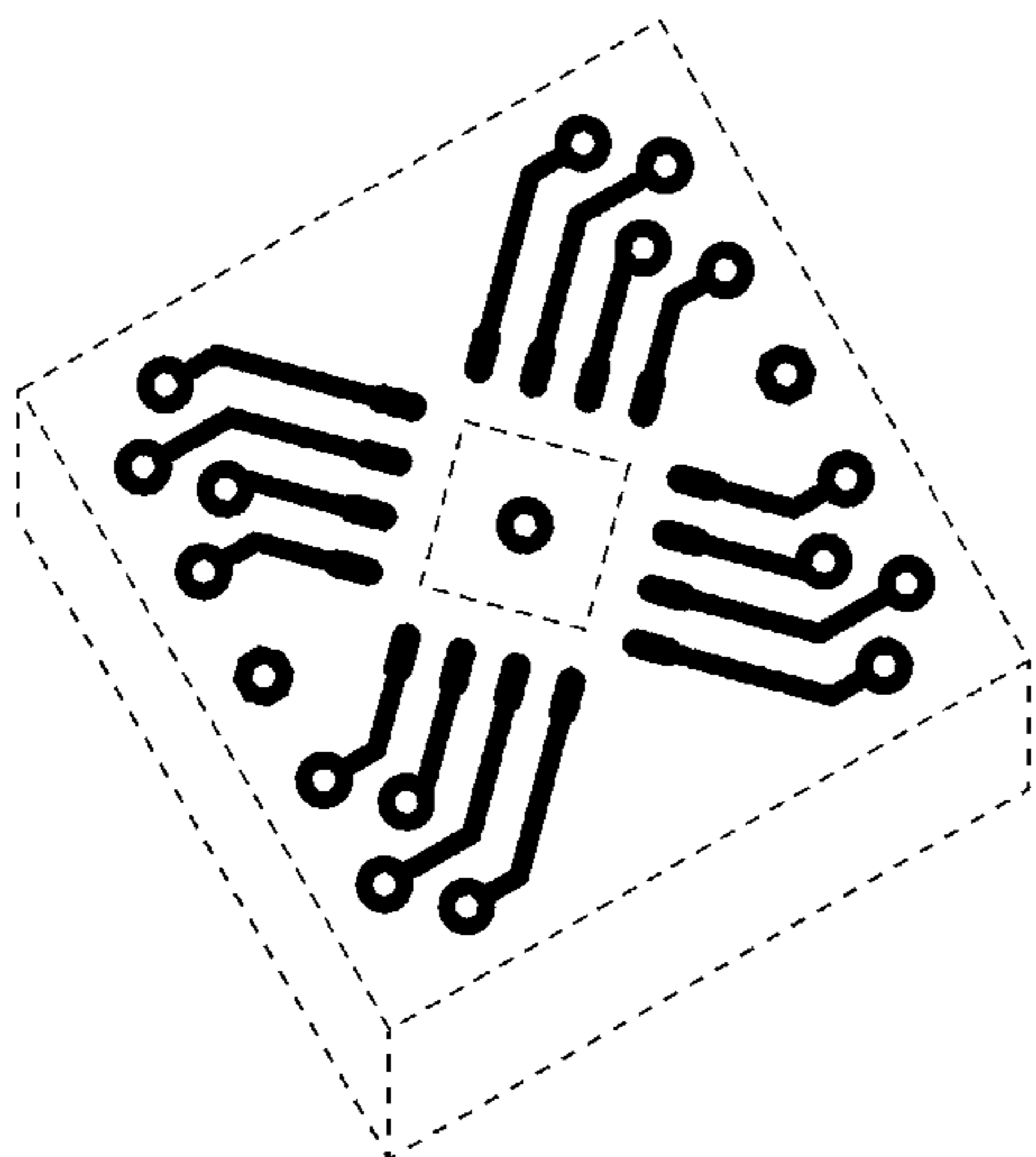
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D474,773 S * 5/2003 Kondo D13/182
D485,536 S * 1/2004 Dang D13/182
6,936,916 B2 * 8/2005 Moxham H01L 23/13
174/256
D552,048 S * 10/2007 He D13/182
D556,158 S * 11/2007 Kong D13/182
7,511,228 B2 3/2009 Yaung et al.
D599,308 S * 9/2009 Blumberg, Jr. D13/182
D605,613 S * 12/2009 Carter D13/182
D639,756 S * 6/2011 Greene, Jr. D13/182
D642,546 S * 8/2011 Greene, Jr. D13/182
D645,039 S * 9/2011 Chen D14/341
8,113,888 B2 * 2/2012 Carter H01R 9/03
439/676
D676,004 S * 2/2013 Lyubachev D13/182
D699,201 S * 2/2014 Petsch D13/182
D768,115 S * 10/2016 Kazanchian D13/182
D794,586 S * 8/2017 Takahashi D13/182
D799,438 S * 10/2017 Takahashi D13/182
D804,437 S * 12/2017 Kantor D13/182
2009/0250246 A1 10/2009 Yaung et al.

* cited by examiner

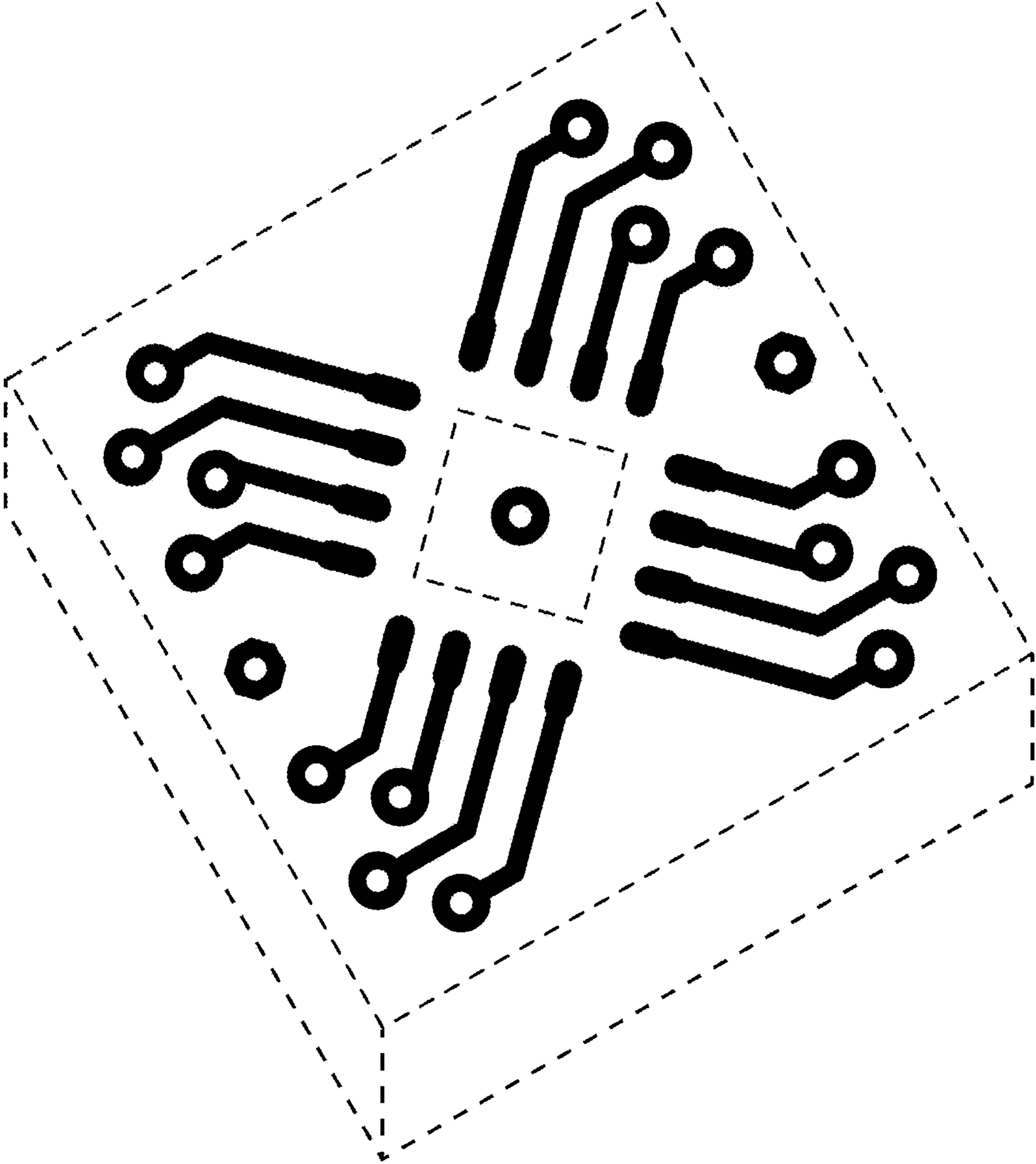


FIG. 1

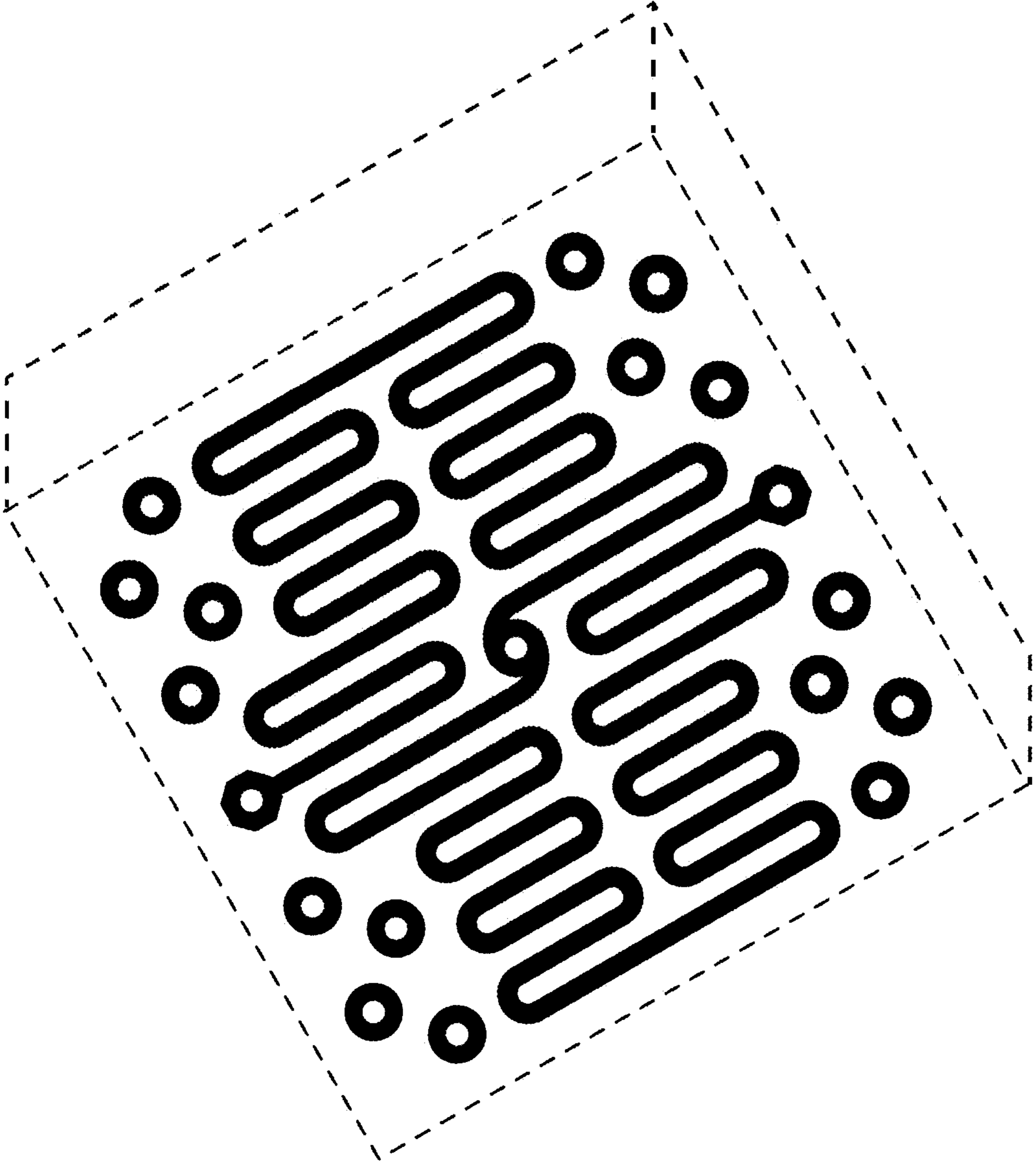


FIG. 2

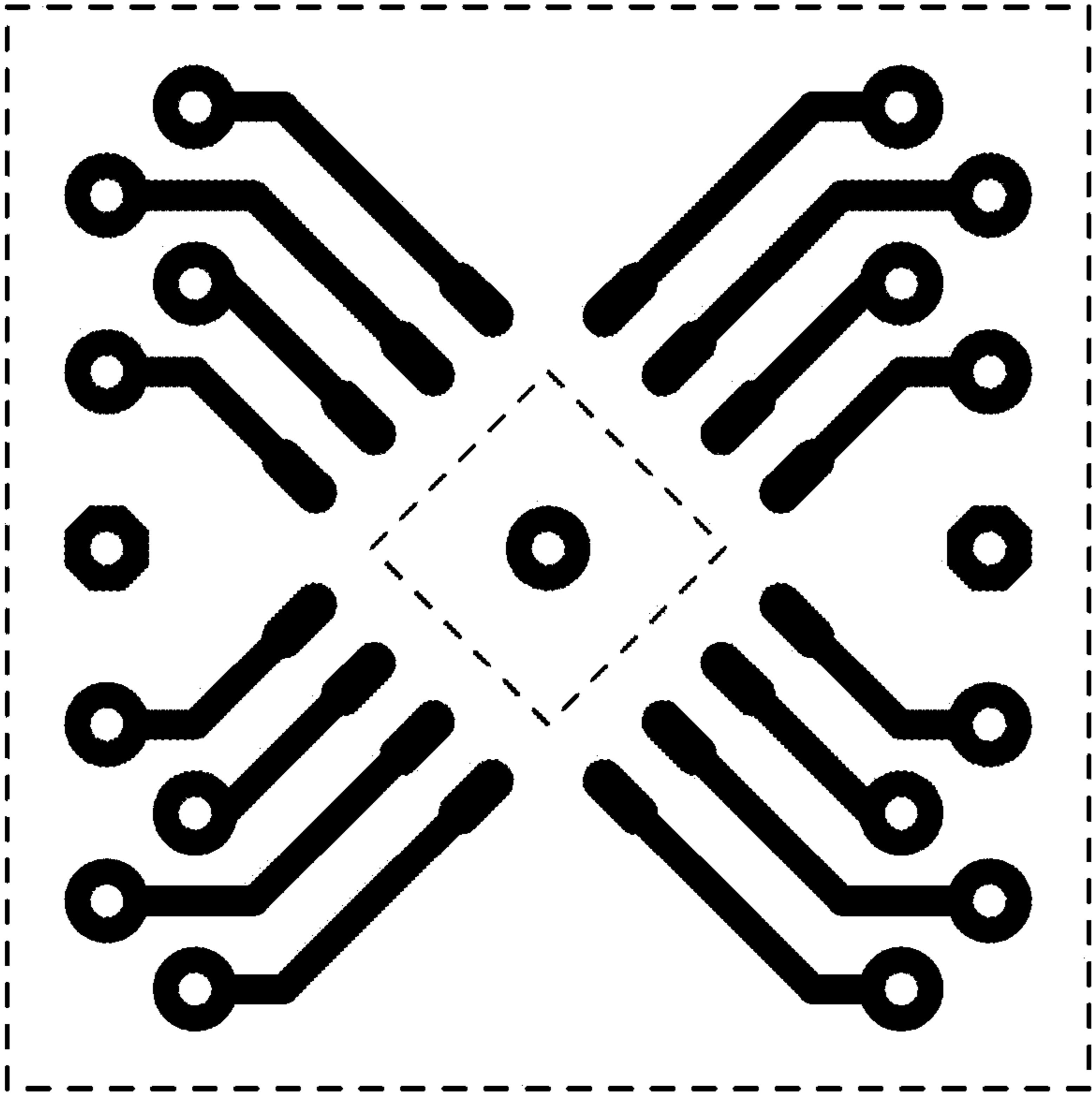


FIG. 3

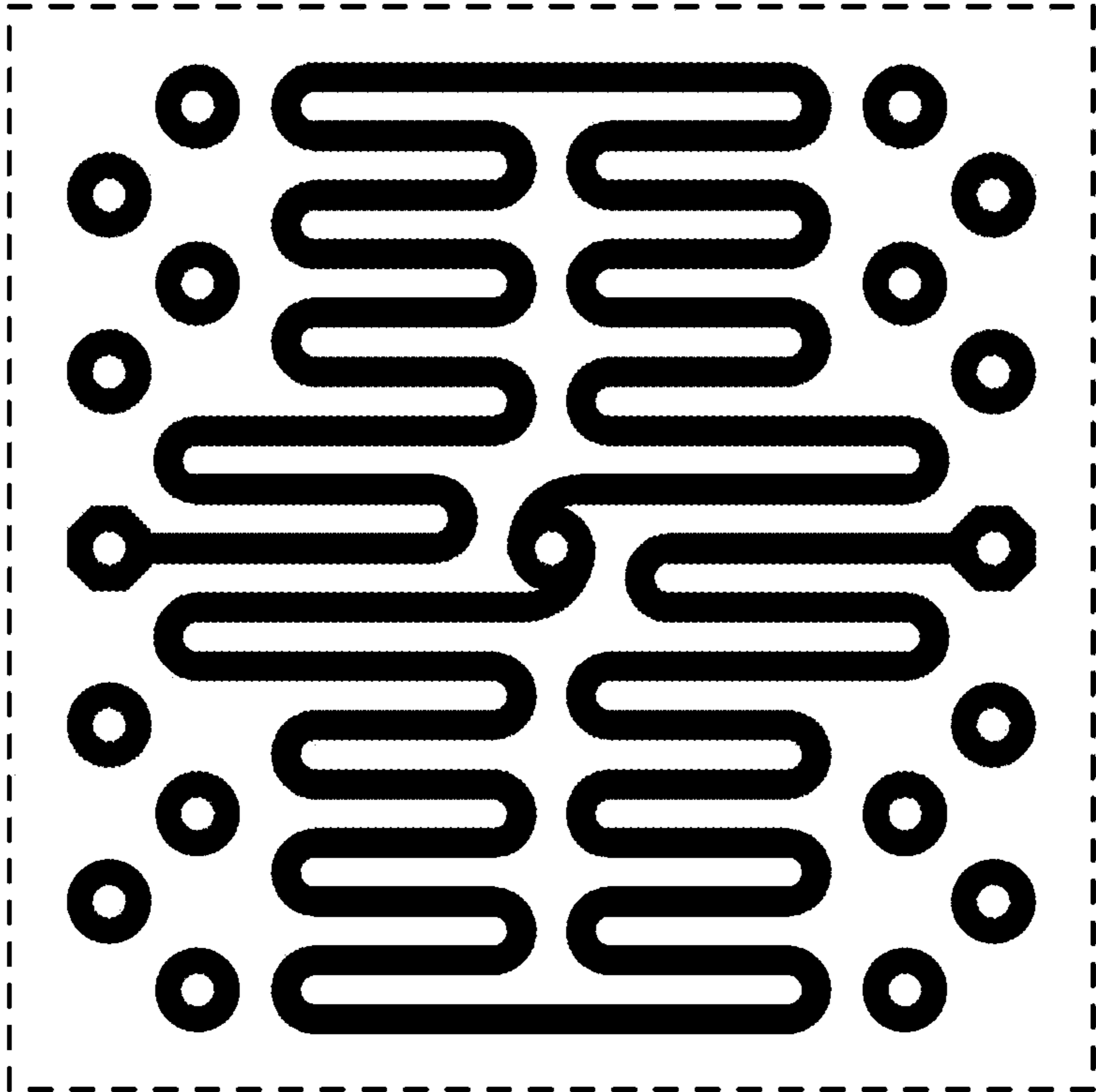


FIG. 4

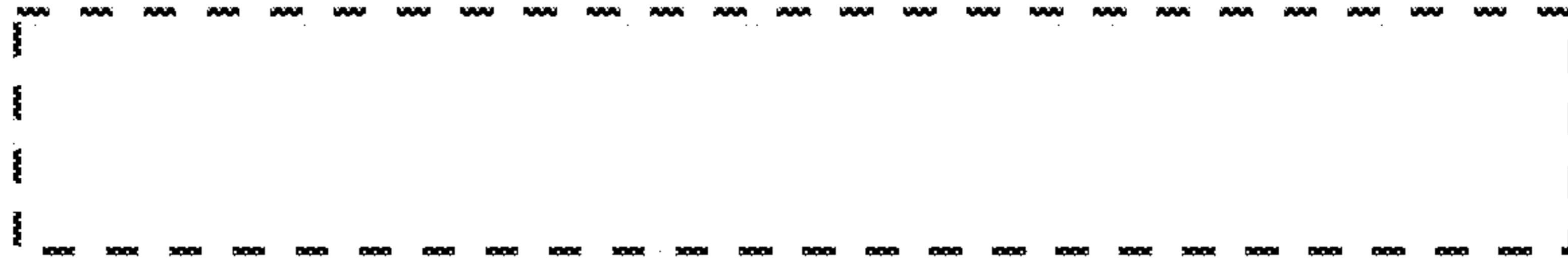


FIG. 5